



BSI Standards Publication

**Damp heat, steady state (unsaturated
pressurized vapour with air)**

National foreword

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TECHNICAL REPORT



Damp heat, steady state (unsaturated pressurized vapour with air)

INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

ICS 19.040

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**DAMP HEAT, STEADY STATE
(UNSATURATED PRESSURIZED VAPOUR WITH AIR)**
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IEC TR 63141, which is a Technical Report, has been prepared by IEC technical committee 104: Environmental conditions, classification and methods of test.

The text of this Technical Report is based on the following documents:

Draft TR	Report on voting
104/834/DTR	104/853A/RVDTR

Full information on the voting for the approval of this Technical Report can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

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INTRODUCTION

Highly accelerated stress test (HAST), is a high temperature (100 °C or more), high humidity steady test of unsaturated pressurized steam of 85 % RH, and is the original test method that was developed for the evaluation of corrosion of packaged semiconductor wiring. This test method, often referred to as HAST, is applied to primarily non-hermetically sealed small electronic components, and has been standardized as a standard test method for evaluating, in an accelerated manner, the resistance to the deteriorative effect of high temperature and high humidity (IEC 60068-2-66). The equipment used for this test method is a chamber, filled with unsaturated water vapour, called a HAST chamber.

However, in life evaluation test conditions, acceleration cannot be obtained without air from the environment being incorporated into the HAST chamber. This test method is referred to as air-HAST.

Examples of the application of air-HAST are whiskers evaluation of lead-free solder, deterioration life evaluation of conductive paste, and deterioration life evaluation of solar cells and are given in this document in order to provide an understanding of air-HAST with the aim, in future, to standardize air-HAST.

The International Electrotechnical Commission (IEC) draws attention to the fact that it is claimed that compliance with this document may involve the use of a patent concerning whisker evaluation given in Clause 5.

IEC takes no position concerning the evidence, validity and scope of this patent right.

The holder of this patent right has assured the IEC that he/she is willing to negotiate licences under reasonable and non-discriminatory terms and conditions with applicants throughout the world. In this respect, the statement of the holder of this patent right is registered with IEC. Information may be obtained from:

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DAMP HEAT, STEADY STATE (UNSATURATED PRESSURIZED VAPOUR WITH AIR)

1 Scope

This document describes a new test method to control the volume of air injected into a conventional HAST chamber filled with water vapour. This document provides an overview of the conventional HAST chamber, an overview of the air-HAST equipment where air is incorporated into the HAST chamber, an example of an air-HAST test apparatus, and application examples of air-HAST.

2 Normative references

There are no normative references in this document.

3 Terms and definitions

For the purposes of this document, the following terms and definitions apply.

ISO and IEC maintain terminological databases for use in standardization at the following addresses:

- IEC Electropedia: available at <http://www.electropedia.org/>
- ISO Online browsing platform: available at <http://www.iso.org/obp>

3.1

galvanic corrosion

corrosion damage induced when two dissimilar materials are coupled in a corrosive electrolyte

3.2

Kirkendall effect

motion of the boundary layer between two metals that occurs as a consequence of the difference in diffusion rates of the metal atoms

3.3

whisker

metallic protrusion which grows up naturally during storage or in use

3.4

HAST

highly accelerated stress test

original test method developed to evaluate the corrosion of the semiconductor wiring at a high temperature of 100 °C or more

3.5

air-HAST

HAST test method with the addition of further air partial pressure in a HAST chamber